## SI-FLY 112 Gbps PAM4, LOW-PROFILE HIGH-DENSITY CABLE SYSTEM



## **FEATURES & BENEFITS**

- Ultra-low profile interconnect adjacent to the IC package
- Up to 16 pairs in an incredibly low 3.8 mm profile
- This extremely low profile allows Si-Fly™ connectors to reside under heat sinks or other cooling hardware
- 112 Gbps PAM4 per lane
- Extreme channel performance enabling 25.6 TB aggregate with a path to 51.2 TB
- Roadmap: Co-packaged interconnect option eludes the BGA and routes signals from the silicon package through a long-reach cable, supporting 5x the signal reach of traditional PCB solutions

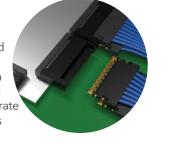


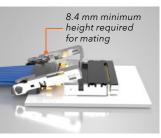
Current

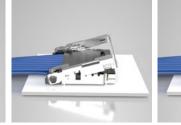
Future

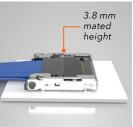
Roadmap: Co-packaged interconnect configuration for advanced 112G+ data rate requirements

F-221 (Rev 08NOV21)









## **KEY SPECIFICATIONS**

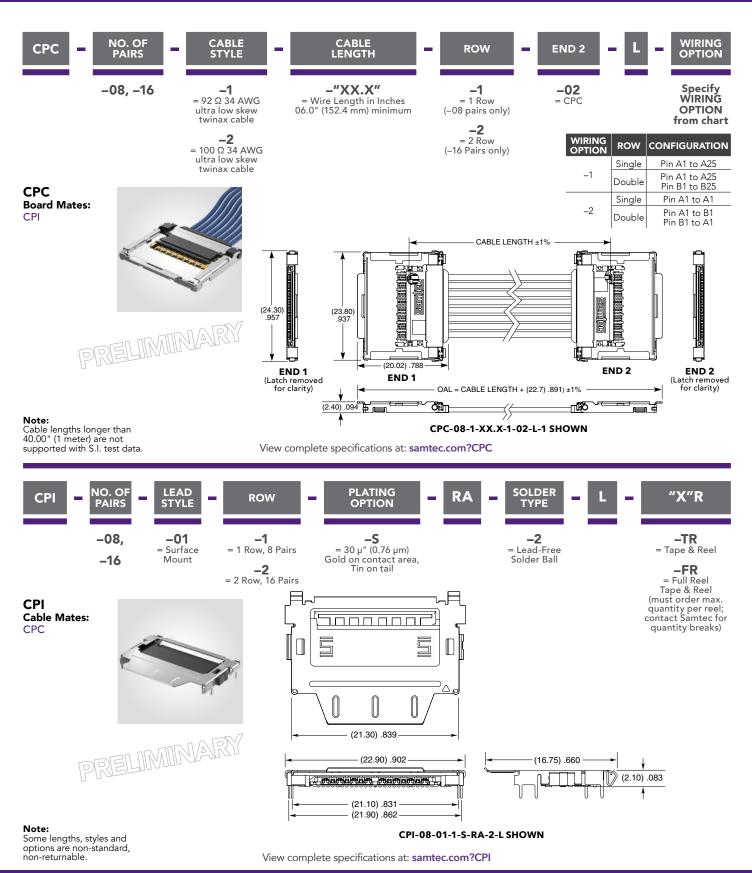
In development: Rugged latching configuration provides a secure connection directly adjacent to the IC package for increased signal integrity performance

CABLE	SIGNAL ROUTING	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING
34 AWG ultra low skew twinax	92 Ω & 100 Ω	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.



## 0.6 mm CO-PACKAGED CABLE & INTERCONNECT



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